## Data Sheet

Tg $150^{\circ} \mathrm{C}$
Td $330^{\circ} \mathrm{C}$

## High Performance Laminate and Prepreg

## IS400 is a proprietary, temperature resistant resin system with a Tg of $150^{\circ} \mathrm{C}$.

It is intended for multilayer Printed Wiring Board (PWB) applications where demanding thermal performance and high reliability are required. IS400 laminate and prepreg products are manufactured using Isola's patented technology, reinforced with electrical grade (E-glass) glass fabric. This system delivers a $330^{\circ} \mathrm{C}$ decomposition temperature and a low Z-axis expansion.

## Product Attributes

High Thermal Reliability

## Typical Market Applications

Automotive \& Transportation

ORDERING INFORMATION:
Contact your local sales representative or visit www.isola-group.com for further information.

Isola Group
3100 West Ray Road
Suite 301
Chandler, AZ 85226
Phone: 480-8936527
Fax: 480-893-1409
info@isola-
group.com

Isola Asia Pacific (Hong Kong) Ltd.
Unit 3512-3522, 35/F
No. 1 Hung To Road, Kwun Tong,
Kowloon, Hong Kong
Phone: 852-2418-1318
Fax: 852-2418-1533
info.hkg@isola-group.com

Isola GmbH Isola Strasse 2 D-52348 Düren, Germany Phone: 49-2421-8080 Fax: 49-2421-808164 info-dur@isolagroup.com

## Product Features

Industry Recognition

- UL File Number: E41625
- RoHS Compliant

Performance Attributes

- CAF resistant

Processing Advantages

## Product Availability

Standard Material Offering: Laminate

- 2 to 93 mil ( 0.05 to 2.4 mm )
- Available in full size sheet or panel form

Copper Foil Type

- HTE Grade 3
- RTF (Reverse Treat Foil)

Copper Weight

- $1 / 2$ to 2 oz ( 18 to $70 \mu \mathrm{~m}$ ) available
- Heavier copper available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Roll or panel form
- Tooling of prepreg panels

Glass Fabric Availability

- E-glass
- Square weave glass


## IS400 Typical Values

| Property |  | Typical Value | Units | Test Method |
| :---: | :---: | :---: | :---: | :---: |
|  |  | Metric (English) | IPC-TM-650 (or as noted) |
| Glass Transition Temperature (Tg) by DSC |  |  | 150 | ${ }^{\circ} \mathrm{C}$ | 2.4.25C |
| Decomposition Temperature (Td) by TGA @ 5\% weight loss |  | 330 | ${ }^{\circ} \mathrm{C}$ | 2.4.24.6 |
| Time to Delaminate by TMA (Copper removed) | A. T260 <br> B. T288 | $\begin{aligned} & >60 \\ & >10 \end{aligned}$ | Minutes | 2.4.24.1 |
| Z-Axis CTE | A. Pre-Tg <br> B. Post-Tg <br> C. 50 to $260^{\circ} \mathrm{C}$, (Total Expansion) | $\begin{gathered} 50 \\ 250 \\ 3.3 \\ \hline \end{gathered}$ | $\begin{gathered} \mathrm{ppm} /{ }^{\circ} \mathrm{C} \\ \mathrm{ppm} /{ }^{\circ} \mathrm{C} \\ \% \end{gathered}$ | $\begin{aligned} & \text { 2.4.24C } \\ & 2.4 .24 \mathrm{C} \end{aligned}$ |
| X/Y-Axis CTE | Pre-Tg | 13 | $\mathrm{ppm} /{ }^{\circ} \mathrm{C}$ | 2.4.24C |
| Thermal Conductivity |  | 0.36 | W/mK | ASTM E1952 |
| Thermal Stress 10 sec @ 288으 (550.4야) | A. Unetched <br> B. Etched | Pass | Pass Visual | 2.4.13.1 |
| Dk, Permittivity | A. @ 100 MHz <br> B. @ 500 MHz | $\begin{aligned} & 4.00 \\ & 3.90 \end{aligned}$ | - | $\begin{aligned} & 2.5 .5 .3 \\ & 2.5 .5 .9 \end{aligned}$ |
| Df, Loss Tangent | A. @ 100 MHz <br> B. @ 500 MHz | $\begin{aligned} & 0.020 \\ & 0.022 \end{aligned}$ | - | $\begin{aligned} & 2.5 .5 .3 \\ & 2.5 .5 .9 \end{aligned}$ |
| Volume Resistivity | A. C-96/35/90 <br> B. At elevated temperature | $\begin{aligned} & 4.0 \times 10^{8} \\ & 7.0 \times 10^{7} \end{aligned}$ | M $\Omega$-cm | 2.5.17.1 |
| Surface Resistivity | A. C-96/35/90 <br> B. At elevated temperature | $\begin{aligned} & 3.0 \times 10^{6} \\ & 5.4 \times 10^{6} \end{aligned}$ | $\mathrm{M} \Omega$ | 2.5.17.1 |
| Dielectric Breakdown |  | $>50$ | kV | 2.5.6B |
| Arc Resistance |  | 120 | Seconds | 2.5.1B |
| Electric Strength (Laminate \& laminated prepreg) |  | 48 (1100) | kV/mm (V/mil) | 2.5.6.2A |
| Comparative Tracking Index (CTI) |  | 3 (175-249) | Class (Volts) | UL 746A ASTM D3638 |
| Peel Strength | A. Low profile copper foil and very low profile copper foil all copper foil $>17 \mu \mathrm{~m}$ [ 0.669 mil ] <br> B. Standard profile copper <br> 1. After thermal stress <br> 2. At $125{ }^{\circ} \mathrm{C}$ ( $257{ }^{\circ} \mathrm{F}$ ) <br> 3. After process solutions | $\begin{aligned} & 1.05(6.0) \\ & 1.45(9.0) \\ & 1.25(8.0) \\ & 1.45(9.0) \end{aligned}$ | N/mm (lb/inch) | $\begin{gathered} 2.4 .8 \mathrm{C} \\ 2.4 .8 .2 \mathrm{~A} \\ 2.4 .8 .3 \\ 2.4 .8 .2 \mathrm{~A} \end{gathered}$ |
| Flexural Strength | A. Length direction <br> B. Cross direction | $\begin{aligned} & 82.0 \\ & 66.6 \end{aligned}$ | ksi | 2.4.4B |
| Tensile Strength | A. Length direction <br> B. Cross direction | $\begin{aligned} & 51.2 \\ & 41.7 \end{aligned}$ | ksi | ASTM D3039 |
| Young's Modulus | A. Length direction <br> B. Cross direction | $\begin{aligned} & 3663 \\ & 3328 \end{aligned}$ | ksi | ASTM D790-15e2 |
| Poisson's Ratio | A. Length direction <br> B. Cross direction | $\begin{aligned} & 0.183 \\ & 0.151 \end{aligned}$ | - | ASTM D3039 |
| Moisture Absorption |  | 0.18 | \% | 2.6.2.1A |
| Flammability (Laminate \& laminated prepreg) |  | V-0 | Rating | UL 94 |
| Relative Thermal Index (RTI) |  | 130 | ${ }^{\circ} \mathrm{C}$ | UL 796 |

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

